502825523 05/27/2014

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

c Version v1.1 EPAS ID: PAT2872119

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHUNICHI MATSUMOTO	12/26/2013
ATSUSHI TANIGUCHI	01/07/2014
TOSHIFUMI HONDA	01/09/2014
YUKIHIRO SHIBATA	12/26/2013
YUTA URANO	01/06/2014

RECEIVING PARTY DATA

Name:	Hitachi High-Technologies Corporation	
Street Address: 24-14, Nishishimbashi 1-chome, Minato-ku		
City:	Tokyo	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14232929

CORRESPONDENCE DATA

Fax Number: (703)610-8686

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 7036108652

Email:sdavis@milesstockbridge.comCorrespondent Name:MITCHELL W. SHAPIRO

Address Line 1: 1751 PINNACLE DRIVE, SUITE 500

Address Line 4: TYSONS CORNER, VIRGINIA 22102-3833

ATTORNEY DOCKET NUMBER:	XA-12517/T3309-20226US01	
NAME OF SUBMITTER:	SOPHIA L. DAVIS	
SIGNATURE:	/Sophia L. Davis/	
DATE SIGNED:	05/27/2014	

Total Attachments: 1

source=XA-12517 Assignment#page1.tif

PATENT REEL: 032969 FRAME: 0352

502825523

ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishi Shimbashi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said. Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

DEFECT INSPECTION METHOD AND DEFECT INSPECTION DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi High-Technologies Corporation,

INVENTOR(S)

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-inpart, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S (発明者フルネーム・	i) サイン)	Date Signed (署名日)	
1).	Shunichi Matsumoto	Shunichi MATSUMOTO	Jecanher. 26, 2013	
2)	Otsush's Tomiquehi	Atsushi TANIGUCHI	January 7, 2014	
3)	Joshfumi (konda	Toshifumi HONDA	Jan 9, 2014	
4).	Yuhihoro Shibata	Yukihiro SHIBATA	Jan 9. 2014 december 26,20	, / 3
5).	Yhota Urano	Yuta URANO	January 6, 2014	
6)				
7).				
8)_	4		_	
9)_				
10)_				

PATENT REEL: 032969 FRAME: 0353

RECORDED: 05/27/2014